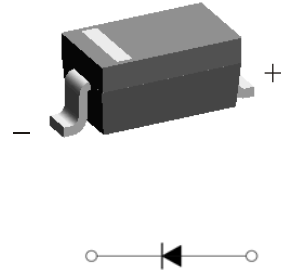
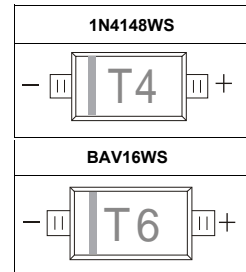


Plastic-Encapsulate Fast Switching Diodes

| PRIMARY CHARACTERISTICS | |
|-------------------------|-------|
| P_D | 200mW |
| V_{RRM} | 100V |
| I_O | 150mA |
| V_{DO} | 1.0V |
| $T_{J,Max}$ | 150°C |

SOD-323 PACKAGE
MARKING: T6,T4

FEATURES

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion
- For General Purpose Switching Applications
- High Conductance
- Moisture Sensitivity Level 1

MECHANICAL DATA

- Case : Molded plastic,SOD-323
- Polarity : As Above Marked
- Terminals :Plated terminals, solderable per MIL-STD-750,Method 2026
- Epoxy : UL94-V0 rated flame retardant

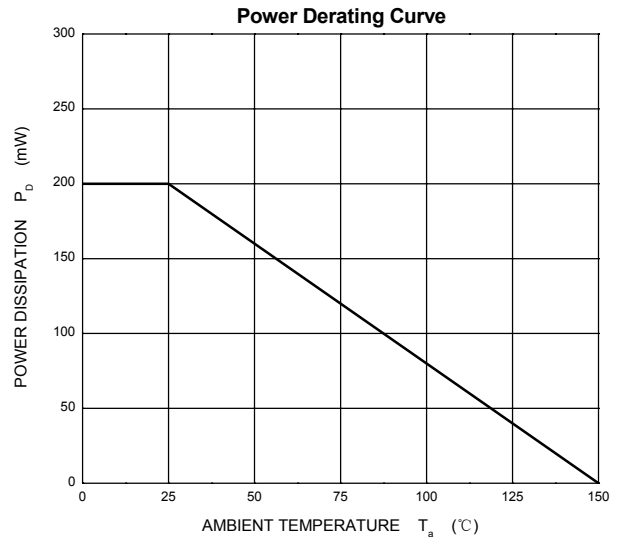
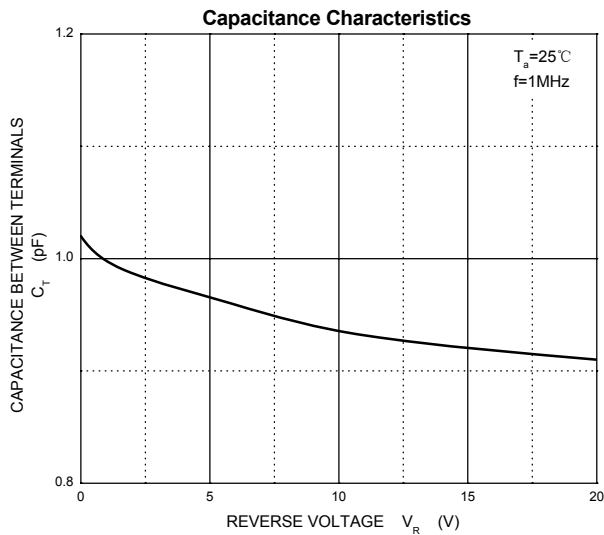
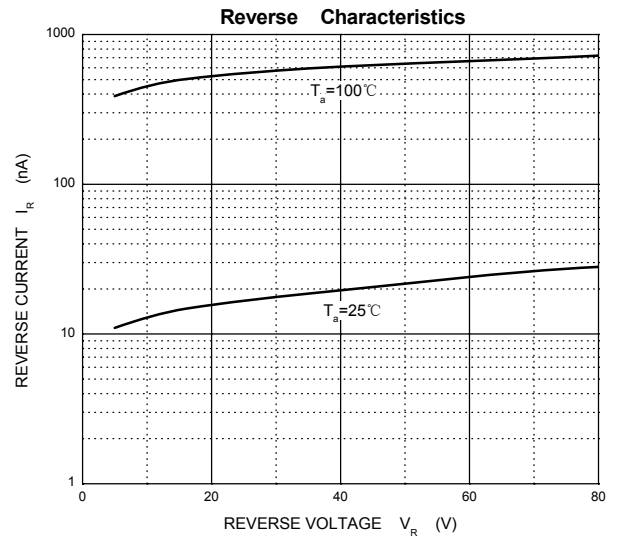
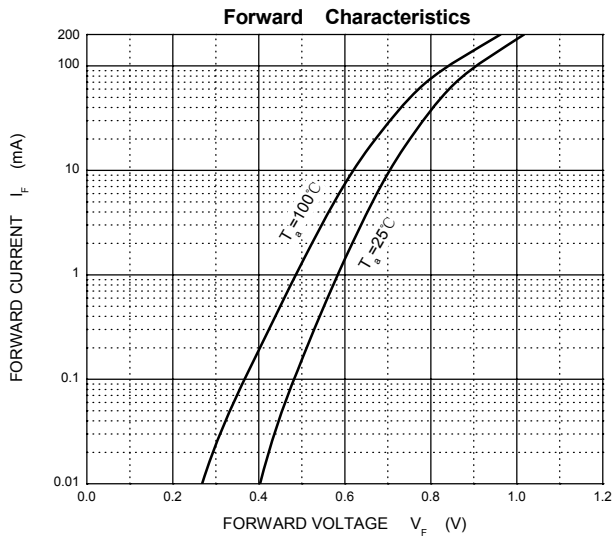
Maximum Ratings and Electrical Characteristics, Single Diode @Ta=25°C

| Parameter | Symbol | Limit | Unit |
|--|-----------------|----------|------|
| Non-Repetitive Peak Reverse Voltage | V_{RM} | 100 | V |
| Peak Repetitive Peak Reverse Voltage | V_{RRM} | 100 | V |
| Working Peak Reverse Voltage | V_{RWM} | | |
| DC Blocking Voltage | V_R | | |
| RMS Reverse Voltage | $V_{R(RMS)}$ | 71 | V |
| Forward Continuous Current | I_{FM} | 300 | mA |
| Average Rectified Output Current | I_O | 150 | mA |
| Peak Forward Surge Current @t=8.3ms | I_{FSM} | 2.0 | A |
| Power Dissipation | P_d | 200 | mW |
| Thermal Resistance Junction to Ambient | $R_{\theta JA}$ | 625 | °C/W |
| Junction Temperature | T_j | 150 | °C |
| Operating/Storage Temperature | T_{STG} | -55~+150 | °C |

Electrical Ratings @Ta=25°C

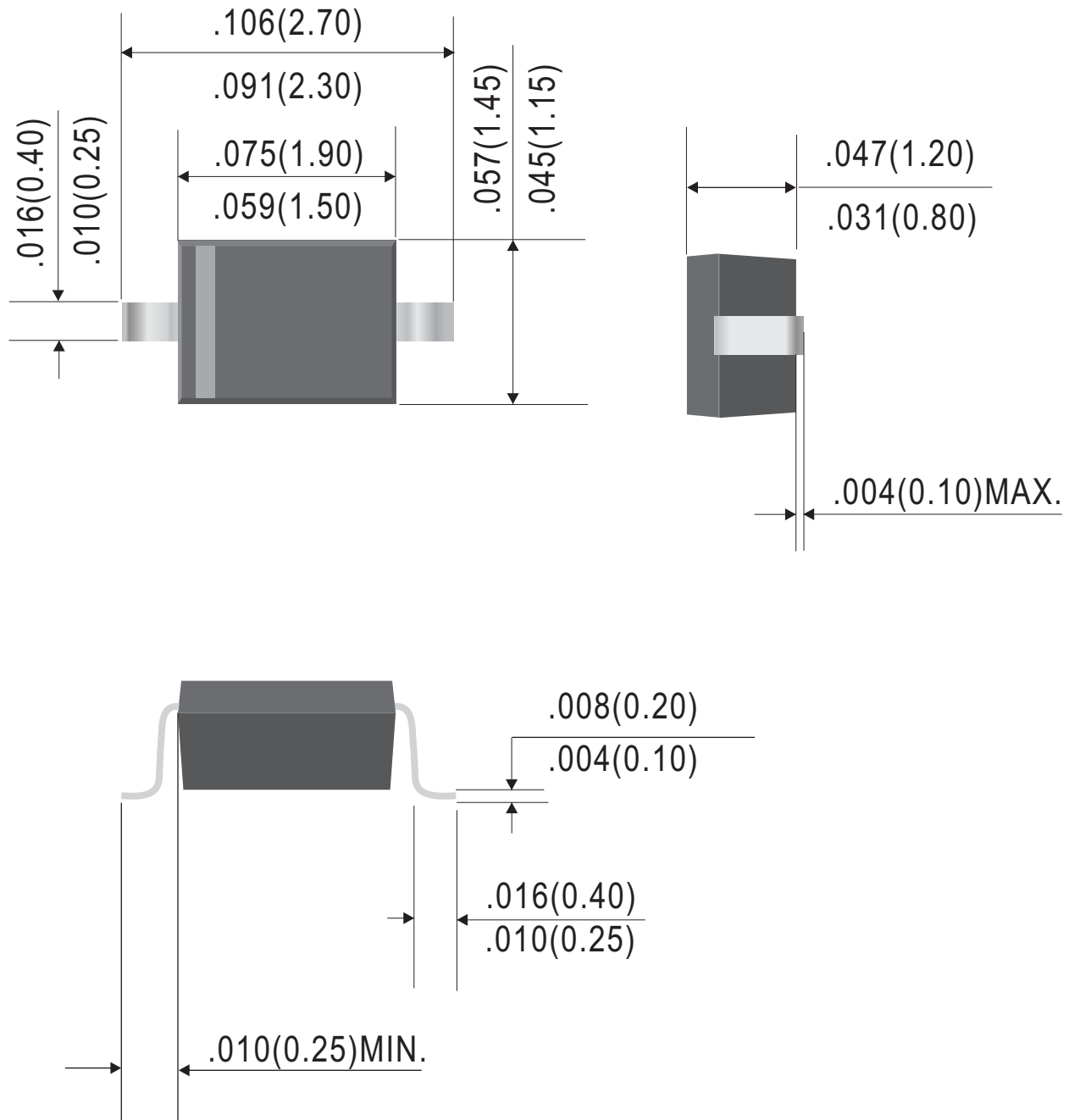
| Parameter | Symbol | Min | Typ | Max | Unit | Conditions |
|-------------------------------|----------|-----|-----|-------|------|--|
| Forward voltage | V_{F1} | | | 0.715 | V | $I_F=1mA$ |
| | V_{F2} | | | 0.855 | V | $I_F=10mA$ |
| | V_{F3} | | | 1.0 | V | $I_F=50mA$ |
| | V_{F4} | | | 1.25 | V | $I_F=150mA$ |
| Reverse current | I_{R1} | | | 1 | μA | $V_R=75V$ |
| | I_{R2} | | | 25 | nA | $V_R=20V$ |
| Capacitance between terminals | C_T | | | 2 | pF | $V_R=0V, f=1MHz$ |
| Reverse recovery time | t_{rr} | | | 4 | ns | $I_F=I_R=10mA$ $I_{rr}=0.1I_R, R_L=100\Omega$ |

Typical Characteristics



Outline Drawing

SOD-323

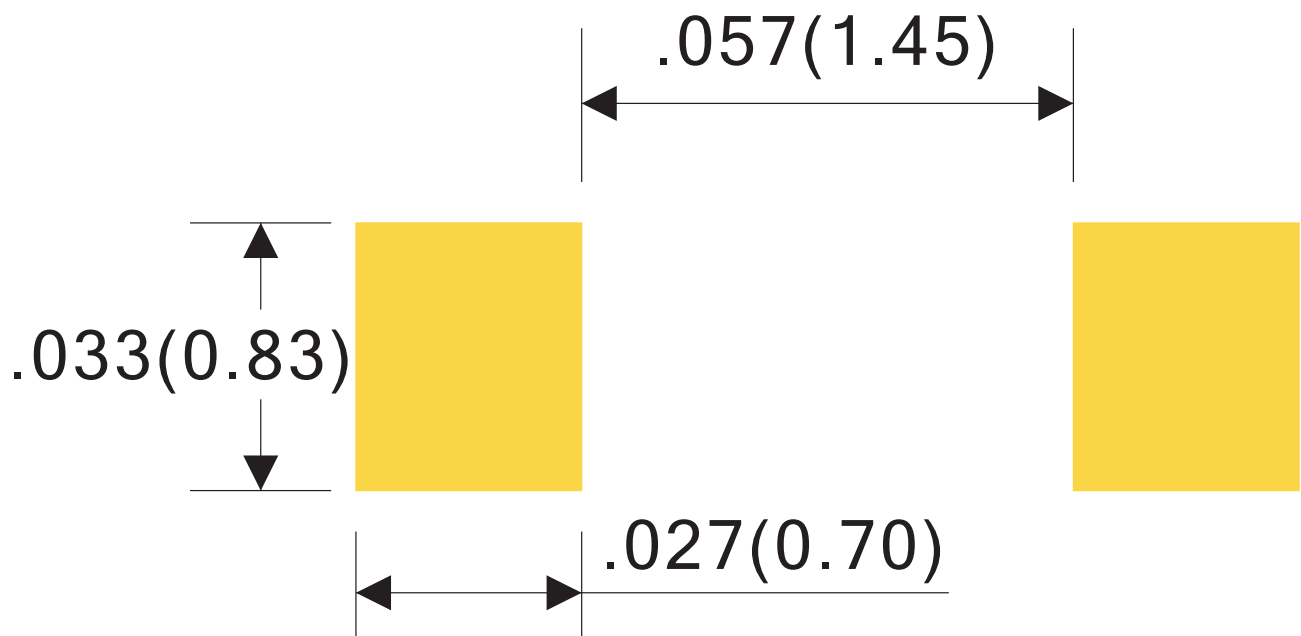


Dimensions in inches and (millimeters)

Rev.D

Suggested Soldering Pad Layout

SOD-323

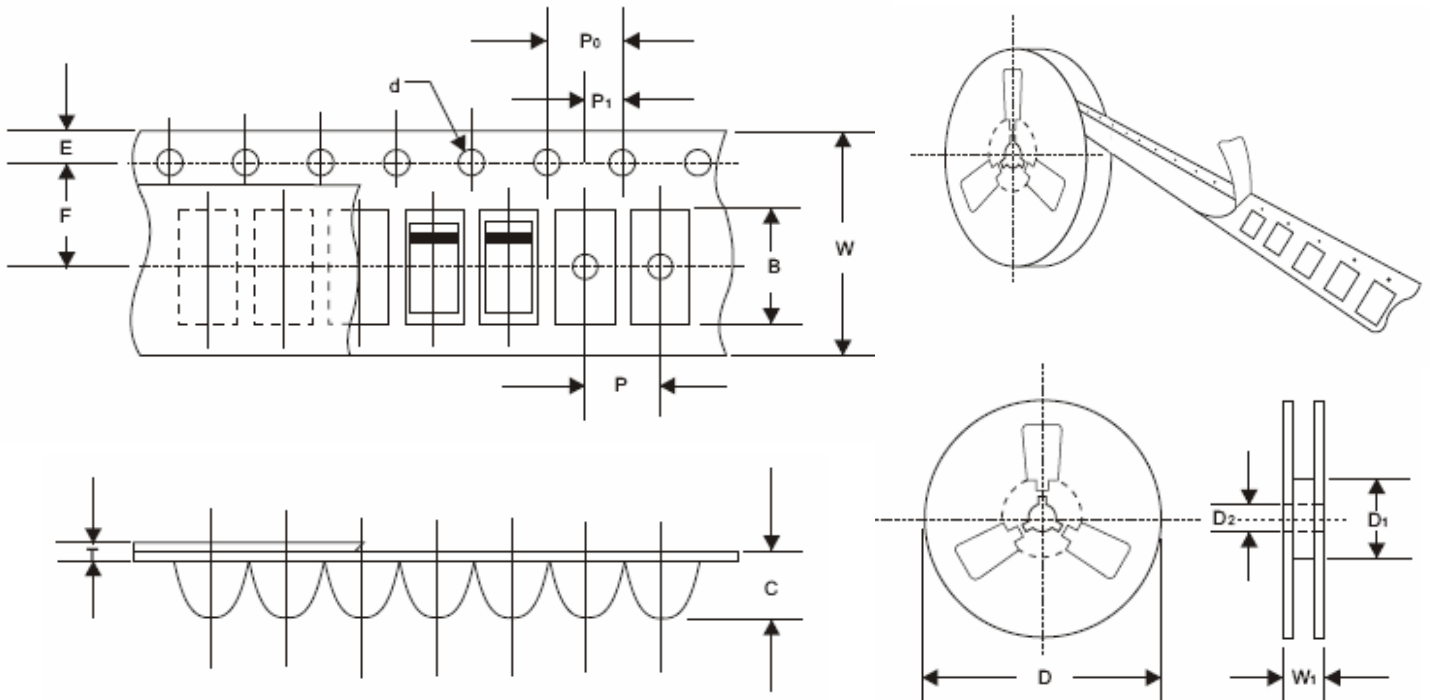


Dimensions in inches and (millimeters)

RevA

Reel Taping Specification - Surface Mount Device/SOD-323

| PACKAGE | PER REEL EA | REEL DIA (m/m) | PER BOX EA | PER CARTION EA |
|---------|-------------|----------------|------------|----------------|
| SOD-323 | 3000 | 178 | 30000 | 240,000 |



| ITEM | SYMBOL | SPECIFICATIONS(mm) | | SPECIFICATIONS(inch) | |
|------------------------|--------|--------------------|--|----------------------|--|
| | | SOD-323 | | SOD-323 | |
| Carrier length | B | 4.5max. | | 0.177max. | |
| Carrier depth | C | 2.4max. | | 0.094max. | |
| Sprocket hole | d | 1.55±0.1 | | 0.061±0.004 | |
| Reel outside diameter | D | 178max. | | 7max. | |
| Reel inner diameter | D1 | 50min. | | 1.969min. | |
| Feed hole diameter | D2 | 13.0±0.2 | | 0.512±0.008 | |
| Sprocket hole position | E | 1.75±0.1 | | 0.069±0.004 | |
| Punch hole position | F | 3.5±0.05 | | 0.1378±0.002 | |
| Punch hole pitch | P | 4.0±0.1 | | 0.157±0.004 | |
| Sprocket hole pitch | P0 | 4.0±0.1 | | 0.157±0.004 | |
| Embossment center | P1 | 2.0±0.05 | | 0.079±0.002 | |
| Overall tape thickness | T | 0.4max. | | 0.016max. | |
| Tape width | W | 8.0±0.3 | | 0.315±0.012 | |
| Reel width | W1 | 14.4max. | | 0.567max. | |

Ordering Information:

| Device PN | Packing |
|---|------------------------|
| Part Number-T ⁽¹⁾ G ⁽²⁾ -WS | Tape&Reel: 3 Kpcs/Reel |

Note: (1) Packing code, Tape&Reel Packing

(2) RoHS product for packing code suffix "G" ; Halogen free product for packing code suffix "H"

*****Disclaimer*****

WILLAS reserves the right to make changes without notice to any product specification herein, to make corrections, modifications, enhancements or other changes. WILLAS or anyone on its behalf assumes no responsibility or liability for any errors or inaccuracies. Data sheet specifications and its information contained are intended to provide a product description only. "Typical" parameters which may be included on WILLAS data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. WILLAS does not assume any liability arising out of the application or use of any product or circuit.

WILLAS products are not designed, intended or authorized for use in medical, life-saving implant or other applications intended for life-sustaining or other related applications where a failure or malfunction of component or circuitry may directly or indirectly cause injury or threaten a life without expressed written approval of WILLAS. Customers using or selling WILLAS components for use in such applications do so at their own risk and shall agree to fully indemnify WILLAS Inc and its subsidiaries harmless against all claims, damages and expenditures.